

Customer Quote 

Receiving Customer Order 

Contract Review 

Enter order in MRP System 

Engineering 

The cam-tool generation 

Part 1. Before the Production

Raw Material Releasing

Multi-layer PCB Design

Inner Layer Imaging

Inner Layer Etching

Resist Stripping

Inner Layer AOI

Post Etch Punch

Inner Layer Oxide

Lay up

Lamination

X-ray Alignment

Drilling

Metallization

Outer Layer Imaging

Pattern Plating

Tin PLating

Resist Stripping

Tin Stripping

Outer Layer Inspection

Surface Prep

Solder Mask Coating

Solder Mask Image

Printing

Final Cure (Masking)

Final Finish

PCB Fabrication

```
graph TD; A[PCB Fabrication] --- B[The Follow-up]; B --- C[Electrical Test]; C --- D[Scoring (IF REQD)]; D --- E[Fabrication]; E --- F[Final Cleaning]; F --- G[Final Visual Inspection]; G --- H[QC And FAI Reporting]; H --- I[Packaging]; I --- J[Invoicing]; J --- K[Shipping];
```

The Follow-up

Electrical Test

Scoring (IF REQD)

Fabrication

Final Cleaning

Final Visual Inspection

QC And FAI Reporting

Packaging

Invoicing

Shipping